

P-Channel Enhancement Mode Power MOSFET

<p>Description</p> <p>The G70P04K uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} -40V ● I_D (at $V_{GS} = -10V$) -70A ● $R_{DS(ON)}$ (at $V_{GS} = -10V$) < 10mΩ ● $R_{DS(ON)}$ (at $V_{GS} = -4.5V$) < 12mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters 	<p>Schematic diagram</p> <p>TO-252</p>		
Device	Package	Marking	Packaging
G70P04K	TO-252	G70P04	2500pcs/Reel

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-40	V
Continuous Drain Current	I_D	-70	A
Pulsed Drain Current (note1)	I_{DM}	-280	A
Gate-Source Voltage	V_{GS}	± 20	V
Power Dissipation	P_D	156	W
Single pulse avalanche energy (note3)	E_{AS}	169	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 To 150	$^\circ\text{C}$

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Ambient	R_{thJA}	20	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Case	R_{thJC}	0.8	$^\circ\text{C}/\text{W}$

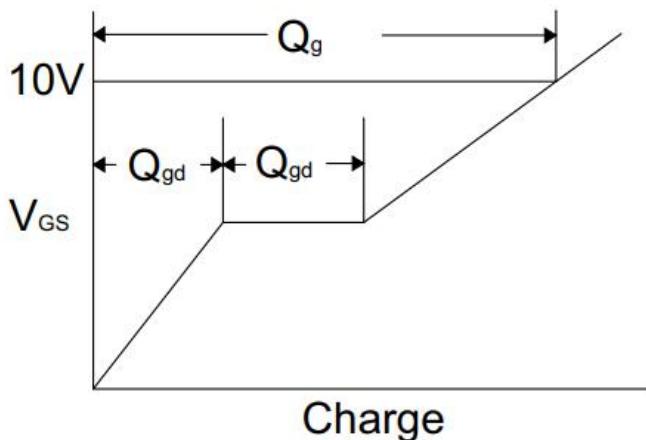
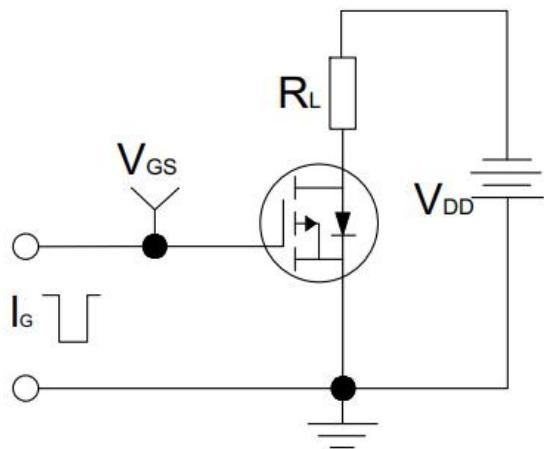
Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Parameters						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-40	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}$	--	--	-1	μA
Gate-Source Leakage	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.4	-2.5	V
Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -10\text{V}, I_D = -10\text{A}$	--	7	10	$\text{m}\Omega$
		$V_{\text{GS}} = -4.5\text{V}, I_D = -8\text{A}$	--	9	12	
Forward Transconductance	g_{FS}	$V_{\text{DS}} = -5\text{V}, I_D = -20\text{A}$	--	58	--	S
Dynamic Parameters						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -20\text{V}, f = 1.0\text{MHz}$	--	4714	--	pF
Output Capacitance	C_{oss}		--	446	--	
Reverse Transfer Capacitance	C_{rss}		--	456	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = -20\text{V}, I_D = -10\text{A}, V_{\text{GS}} = -10\text{V}$	--	42	--	nC
Gate-Source Charge	Q_{gs}		--	7	--	
Gate-Drain Charge	Q_{gd}		--	9.5	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = -20\text{V}, I_D = -10\text{A}, R_G = 3\Omega$	--	10	--	ns
Turn-on Rise Time	t_r		--	18	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	38	--	
Turn-off Fall Time	t_f		--	24	--	
Drain-Source Body Diode Characteristics						
Continuous Body Diode Current	I_S	$T_C = 25^\circ\text{C}$	--	--	-26	A
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{\text{SD}} = -8\text{A}, V_{\text{GS}} = 0\text{V}$	--	--	-1.2	V
Reverse Recovery Time	T_{rr}	$I_S = -10\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = -100\text{A}/\mu\text{s}$	--	40	--	ns
Reverse Recovery Charge	Qrr		--	42	--	ns

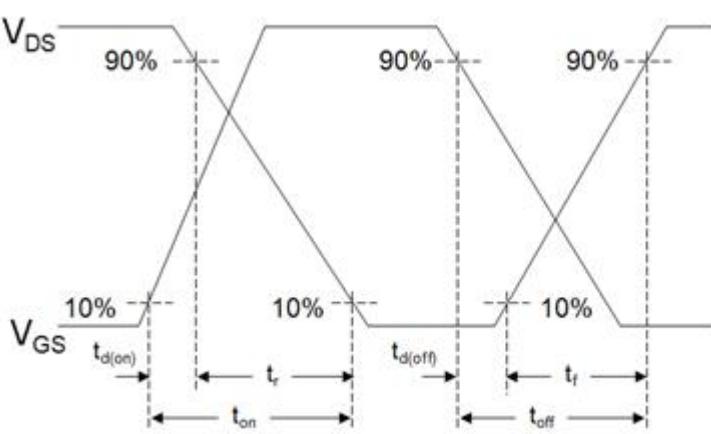
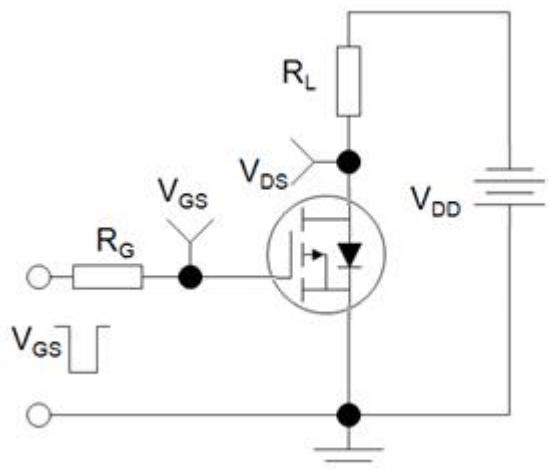
Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. Identical low side and high side switch with identical R_G
3. EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=40\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_g=25\Omega$

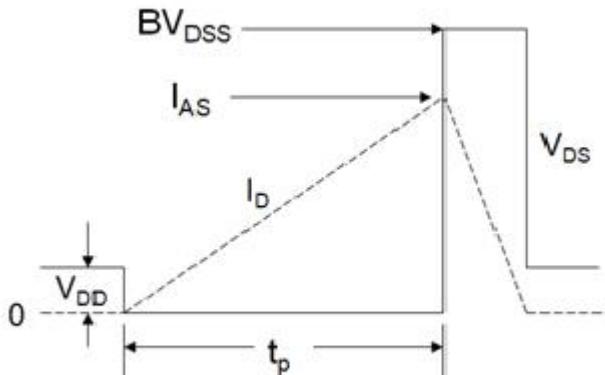
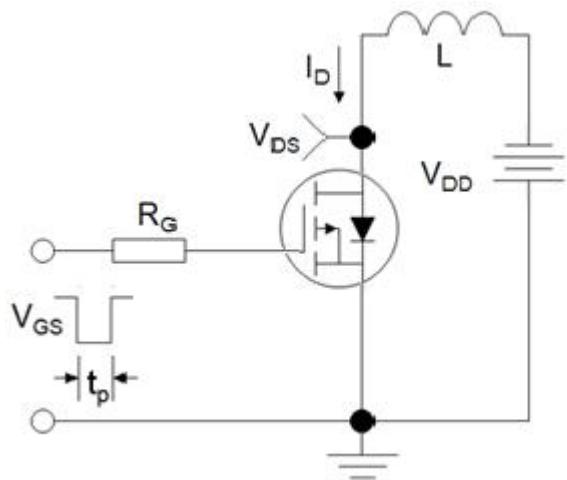
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

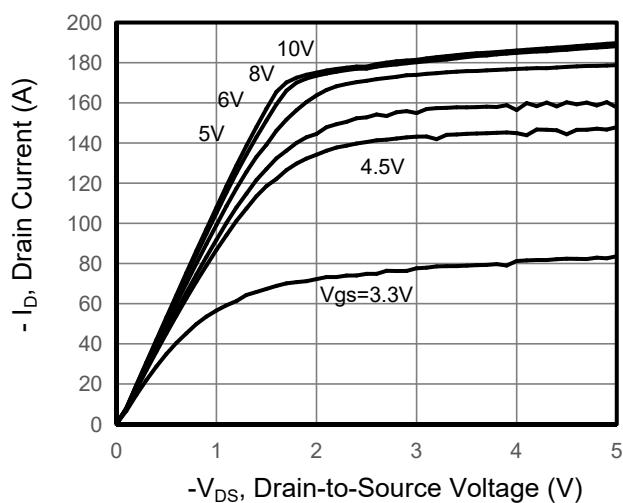


Figure 2. Transfer Characteristics

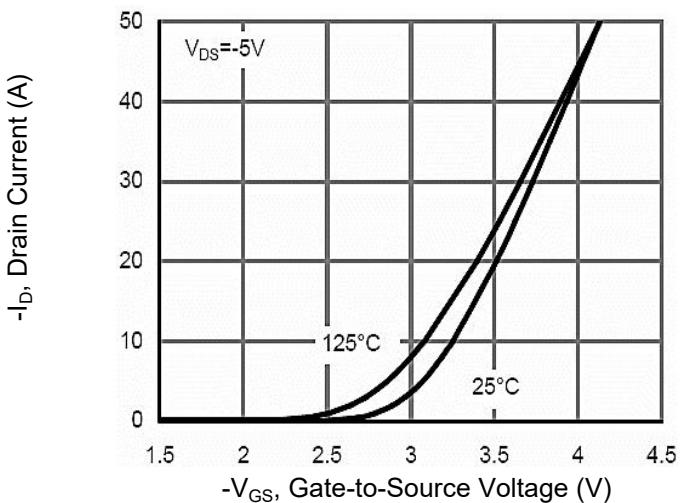


Figure 3. Gate Charge

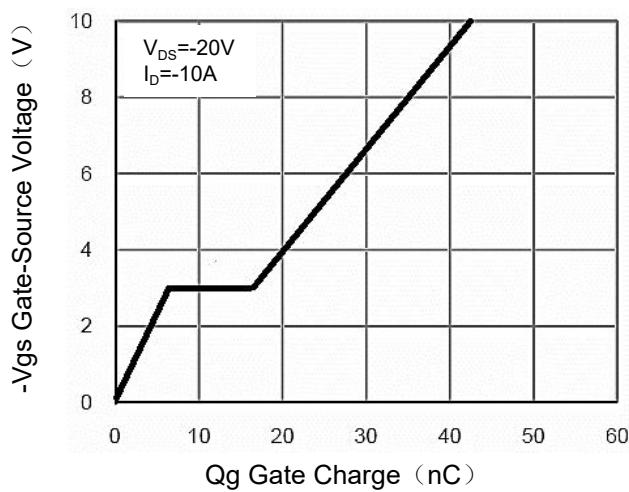


Figure 4. Drain Source On Resistance

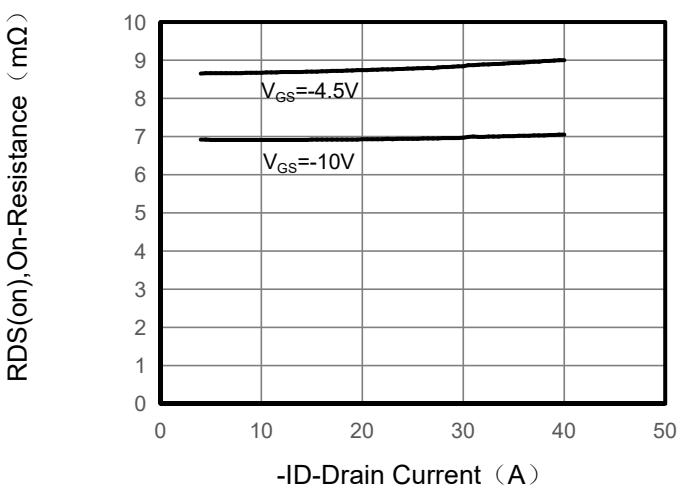


Figure 5. Capacitance

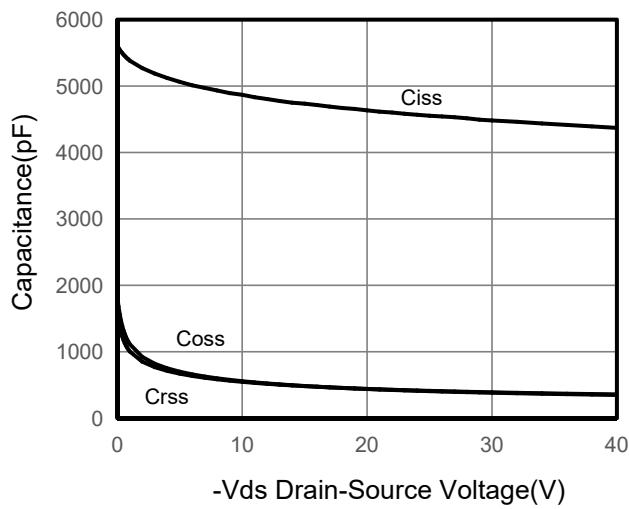
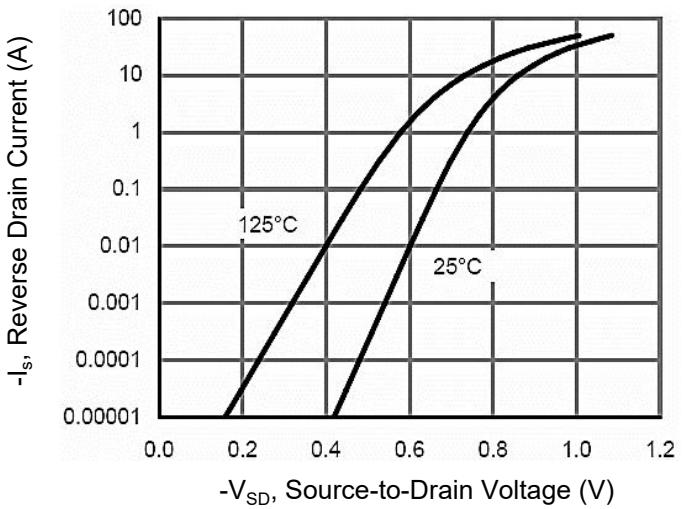


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

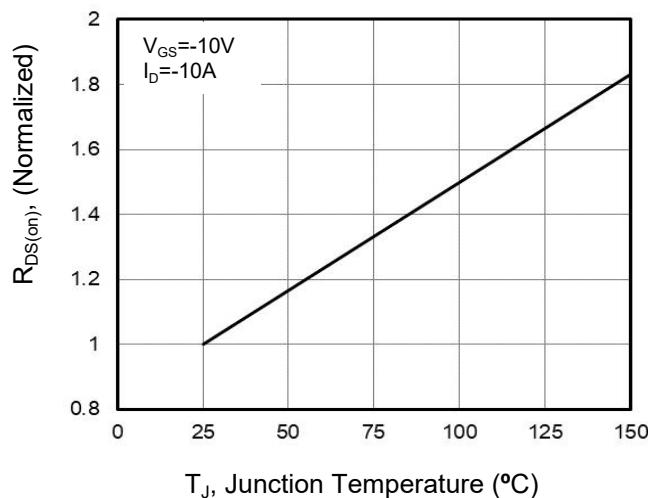


Figure 8. Safe Operation Area

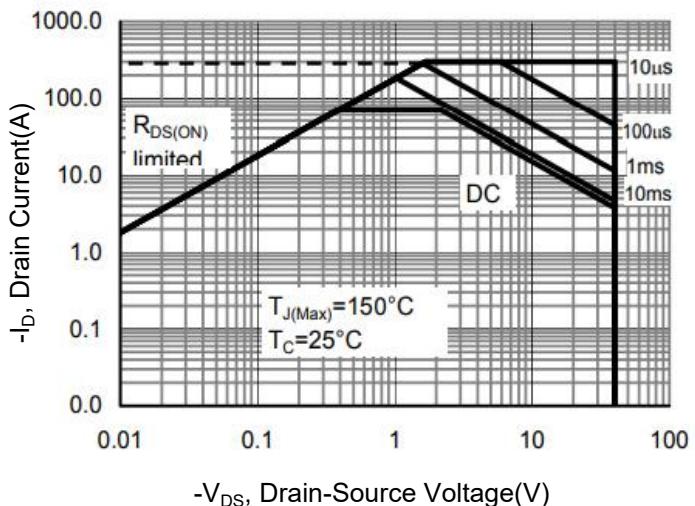
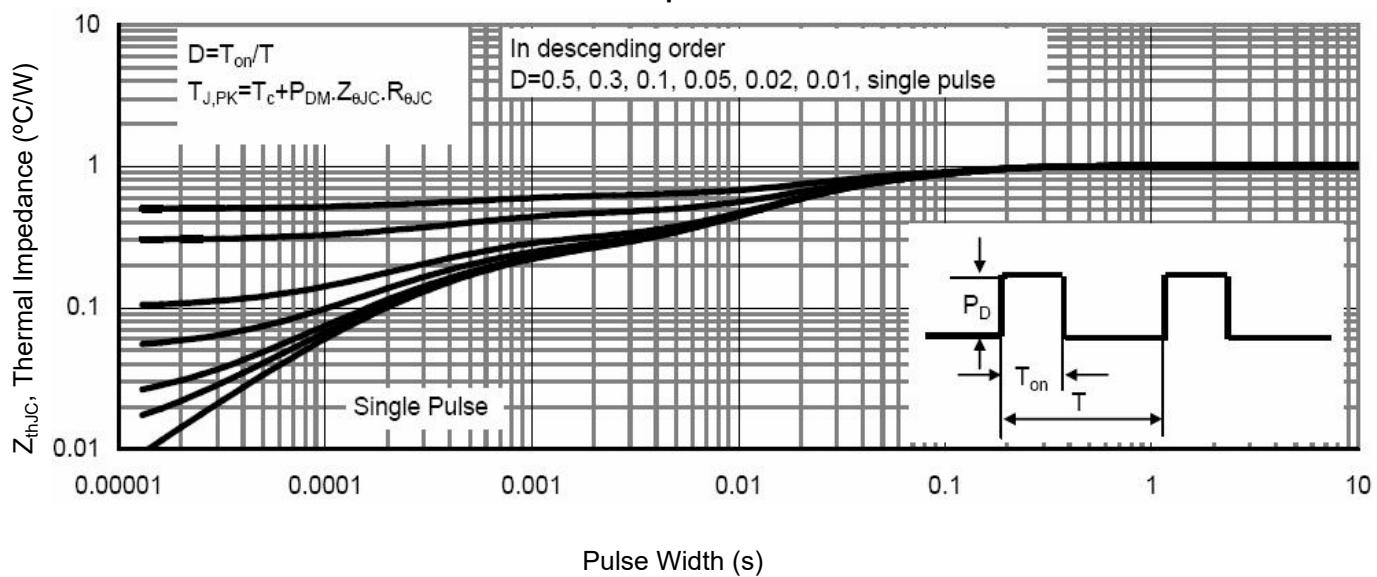
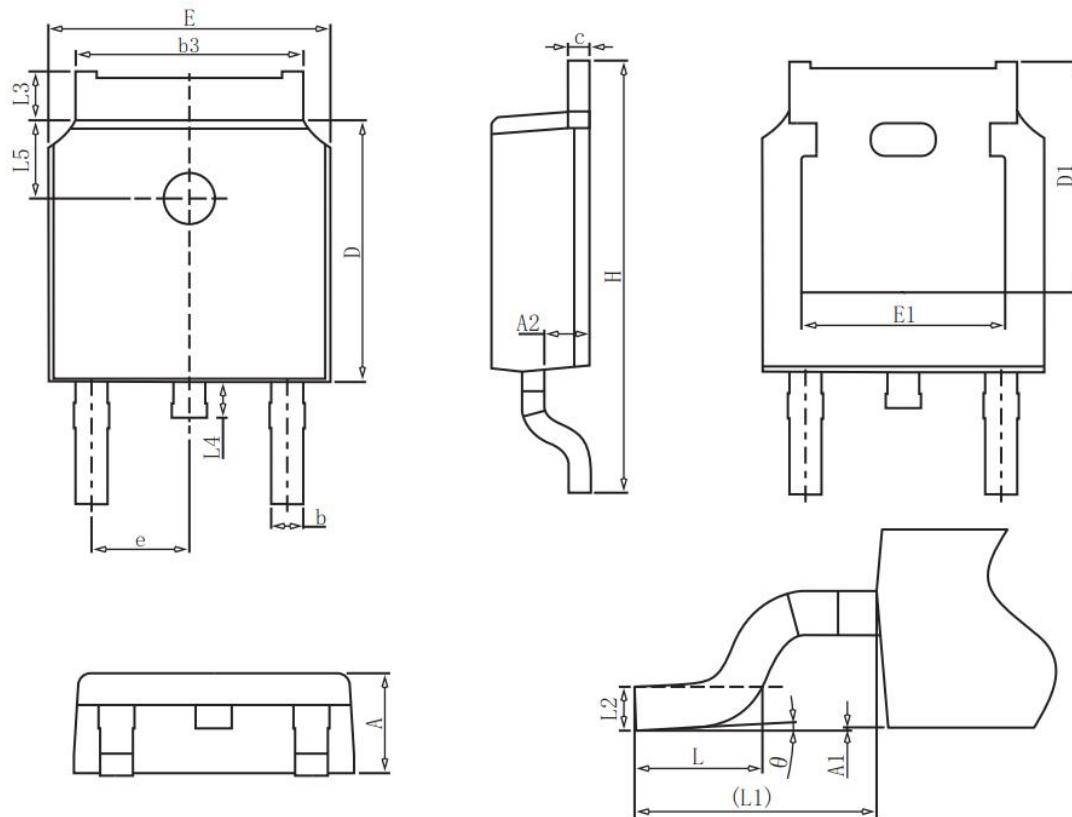


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



Symbol	Dimensions in Millimeters		
	MIN.	NOM.	MAX.
A	2.2	2.3	2.4
A ₁	0		0.2
A ₂	0.97	1.07	1.17
b	0.68	0.78	0.9
b ₃	5.2	5.33	5.5
c	0.43	0.53	0.63
D	5.98	6.1	6.22
D ₁	5.30REF		
E	6.4	6.6	6.8
E ₁	4.63		
e	2.286BSC		
H	9.4	10.1	10.5
L	1.38	1.5	1.75
L ₁	2.90REF		
L ₂	0.51BSC		
L ₃	0.88		1.28
L ₄	0.5		1
L ₅	1.65	1.8	1.95
θ	0°		8°